



Qualification Description	Qualification of RFDA0057 as a reliable product		
Package Type	7.0 mm x 7.0 mm Module	Process Technology	InGaP HBT/ GaAs pHEMT / Si CMOS
Qualification #	11-Qual-1540	Date Issued	Jun 22, 2011

FOR IMPORTANT INFORMATION REGARDING THESE MATERIALS INCLUDING DISCLAIMERS REGARDING USE IN CERTAIN APPLICATIONS, SEE STANDARD DISCLAIMER FOR PRODUCT DOCUMENTS

Test Name	Test Standard and Conditions	# Samples x # Lots	Test Results		
High Temperature Operating Life	JESD22-A108, 1000 hrs	22 x 3 lots	Pass		
Highly Accelerated Temperature and Humidity Stress	JESD22-A110 110°C, 85% RH, Biased, 264 hours Preconditioning per JESD22-A113 MSL 3	22 x 3 Lots	Pass		
ESD Human Body Model	JESD22-A114	3 x 1 Lot per Level	Pass 1000V, Class 1C		
ESD Charged-Device Model	JESD22-C101	3 x 1 Lot per Level	Pass 2000V, Class IV		
IC Latch-Up Test	JESD78 Class I : +25°C, Level A : ±100 mA	6 x 1 Lot	Pass		
Moisture Sensitivity Level	IPC/JEDEC J-STD-020	22 x 3 lots	Pass	MSL 3	260°C
Temperature Cycling	JESD22-A104, 500 cycles Condition G (-40°C/+125°C), Soak Mode 2	22 x 3 lots loose piece	Pass		
Temperature Cycling (On Board)	JESD22-A104 Condition G: -40°C to +125°C, 500 Cycles Soak Mode 2 : 5 min Dwell Preconditioning per JESD22-A113 MSL 3	22 x 3 Lots	Pass		
High Temperature Storage	JESD22-A103, 1000 hours Condition B (150°C)	22 x 3 lots	Pass		
Solderability	JESD22-B102 Condition A (1 hr steam aging)	22 x 3 lots	Pass		
Characterization	JESD86 -40°C to +85°C	2 x 3 lots	Pass		
Conclusion	This product has passed the RFMD Qualification Requirements for production				

Sample size and lot quantities reported are the minimum required for this qualification.